

CT SERIES



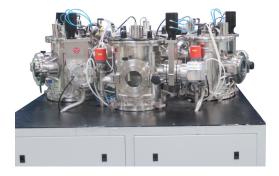
The cluster tool (CT) series combines multiple PVD and CVD process capabilities into a single tool to provide maximum processing options. The ability to deposit films using a range of techniques in the same run enables fabrication of advanced multilayer stacks and device architectures. Each module can be configured individually to meet the technological requirements of the user, while also being extendable for future expansion.

CHAMBER CONFIGURATIONS



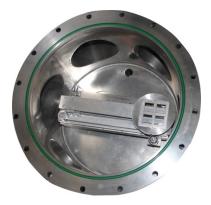


Manual Substrate Transfer





Automated Substrate Transfer



Telescopic transfer arm for indexing and substrate transfer



Showerhead electrode for PECVD



Magnetron sputtering

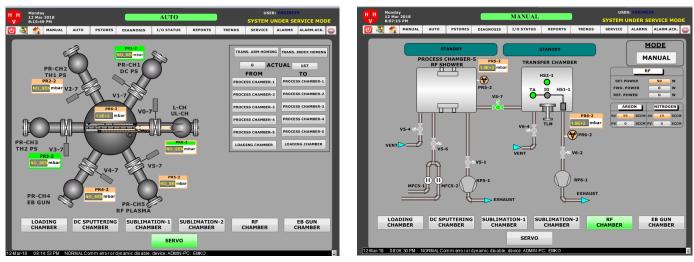


Electron beam evaporation

SPECIFICATIONS

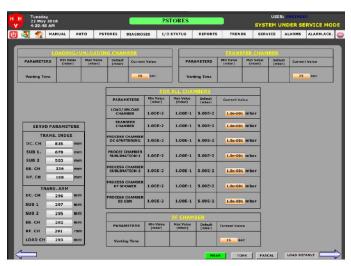
CHAMBER SIZE	Maximum chamber size: 450 mm (Ø) X 500 mm (H)
HV PUMPING OPTIONS	Turbo and Cryo pumps of suitable capacity
ROUGHING/BACKING OPTIONS	Rotary/Dry
BASE PRESSURE	Up to 10 ⁻⁷ mbar
SUBSTRATE SIZE	Maximum upto 150 mm diameter
SUBSTRATE HOLDER	Rotary, Watercooled, Heated, Bias and Z shift

CONTROL OPTIONS





Manual Mode



Instrument Settings

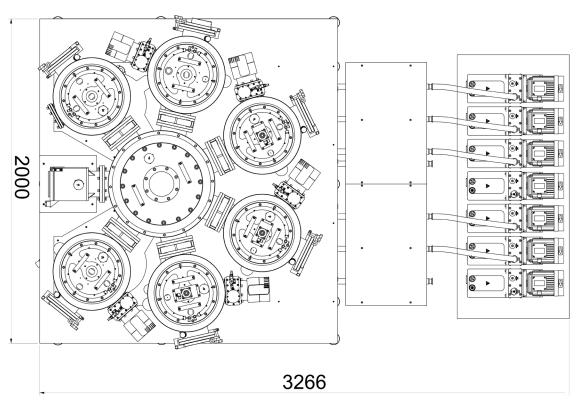
FEATURES

- Modular design with up to 5 process chambers
- Manual or automated substrate transfer
- Sample heating, cooling, biasing and cleaning options
- PC/PLC controlled recipes for automated processes
- Advanced data logging and process tracking options
- Interlocks for safe operation

APPLICATIONS

- Semiconductors
- Optical coatings
- Photovoltaics
- Metal coatings
- Organic Electronics
- Hybrid coatings

LAYOUT



All dimensions in mm Representative footprint. Actual dimensions will depend on system configuration



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